



Product Change Notification

104450 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geography location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmo.pcn@intel.com

Asia Pacific Contact: apacgccb@intel.com

Europe Email: eccb@intel.com

Japan Email: jcb.ijkk@intel.com

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Product Change Notification

Change Notification #: 104450 - 00
Change Title: Intel® NetStructure™ ZT 5085 and ZT 5088 12U Redundant Host Packet Switched Platform, PCN 104450-00, FYI, Product improvements
Date of Publication: October 04, 2004

Type of Change Notification:

FYI - (For Your Information)

Key Characteristics of the Change:

Product Design

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	Jan 01, 2005
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Description of Change to the Customer:

As part of Intel's initiative to increase product performance and reliability, the following improvements will be made to current Intel® NetStructure™ ZT 5085 and ZT 5088 12U Redundant Host Packet Switched Platforms.

1. Power supply cage tolerance changes - Reduction of bends on power supply cage design to tighten tolerance as stack up of multiple sheet metal bends hinder properly seating power supplies into connectors. Solid wall on side of power module without cutouts to improve airflow and PEM cooling
2. Rack Mount brackets - Removed 9 of the 10 cutouts from the rack mount brackets to improve manufacturability and reduce labor machining time at supplier. One cutout needs to remain to allow access to the holes in the side of the chassis.
3. RPIO cage - Redesigned RPIO Cage to use a thicker gauge material, as opposed to doubling thickness of thinner gauge sheet metal to improve rigidity. Other changes include redesigning bracket mount for rear cover and cable guards into existing metal sheet to improve manufacturability
4. Larger perforation in rear exhaust and front vent covers to improve airflow and chassis cooling, and changes to bracket lower rear cover
5. New fan tray, fan cage side panels, cutouts removed - more robust for better air flow control. New fan tray will not be compatible with older ZTxxxx chassis.
6. Other enhancements to improve reliability:
 - 1 piece bottom/rear card guide alignment
 - Tolerances for fan tray clip bracket changing
 - Add fan tray Cable clips
 - Dimple on top of chassis
 - New sheet metal manufacturer

New chassis manufacturer

7. Product code changes from ZTxxxx to MPCHCxxxx

Customer Impact of Change and Recommended Action:

The changes will not require any application changes by the customer. These are mechanical only changes and do not affect the operation of applications. Customers may want to validate their applications but there should be no changes required.

The new fan tray assembly is not compatible with the existing chassis, it will only work with the new chassis. The new fan tray will ship with all new chassis. We will continue to maintain and sell inventory of the existing fan tray for customers that may require spares.

1. Electrically the same as their predecessor - Backplane formats remain the same

2. Mechanical Improvements - Higher tolerances improve fit and rigidity and simplified assembly for improved product availability

3. Chassis and payload reliability

- Air flow improved by 46% - 370 to 540 lfm
- Improved fans (not compatible with older chassis)
- Lower internal temperature rise < 5deg C above ambient
- Better control of fan speeds (fans run nominally at 80%)
- Acoustic noise improvement by 5 db.

Intel will be completing a full qualification of the changes. Another PCN will be issued to inform customers of the actual change and implementation date once validation is complete.

Products Affected / Intel Ordering Codes:

System Products Table

Affected Product Code	Pre-Change MM#	Post-Change MM#	Pre-Change TA	Post-Change TA	Pre-Change Subassembly	Post-Change Subassembly
ZT5085AC 845904	845904					
ZT5085DC 845906	845906					
ZT5088AC 845907	845907					
ZT5088DC 845912	845912					

Reference Documents / Attachments:

Document:

Location #:

PCN Revision History:

Date of Revision:

October 4, 2004

Revision Number:

00

Reason:

Originally Published PCN